


### 4 LAYER STACKUP

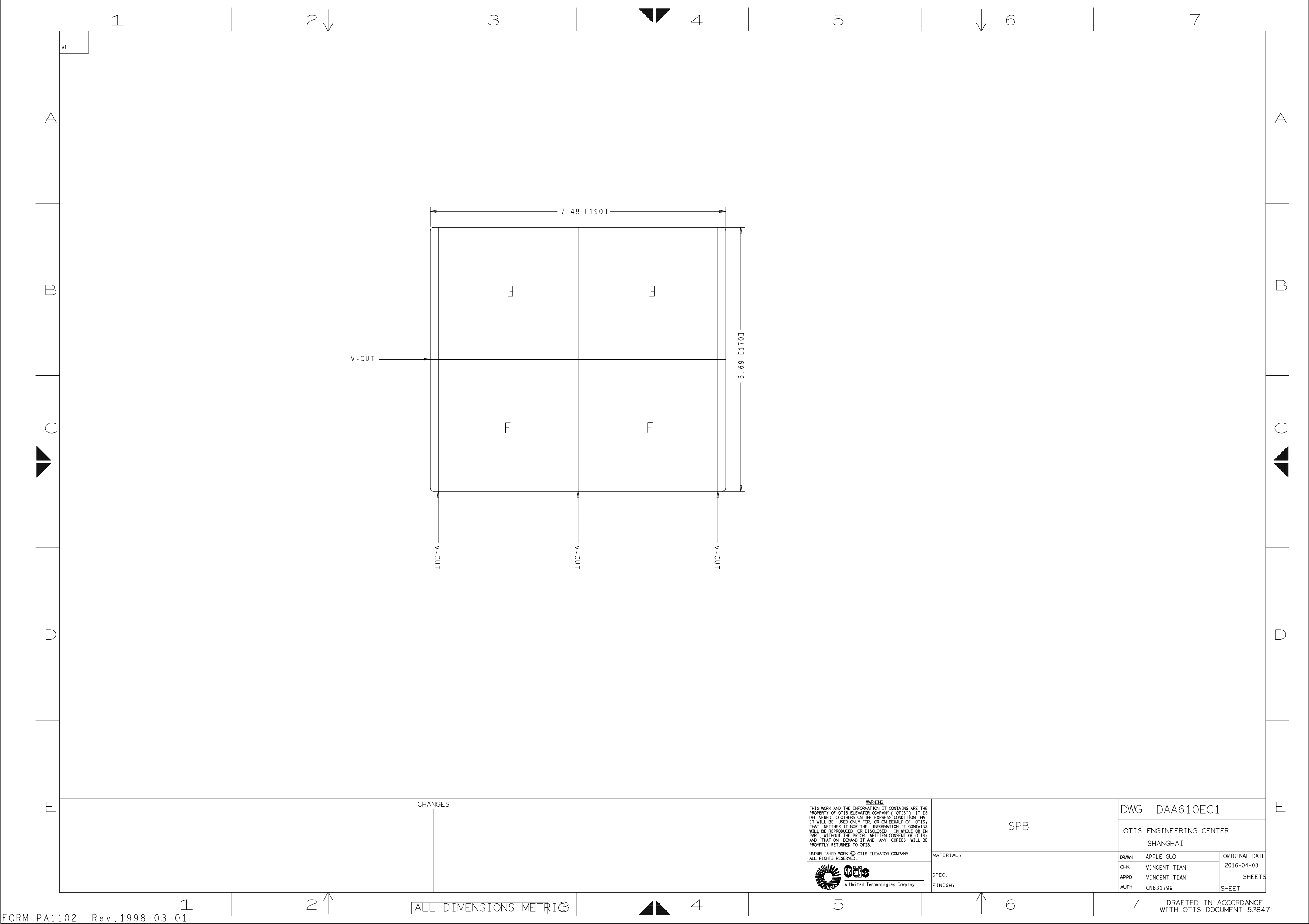
FINISHED THICKNESS .062 +/- .004 AFTER FABRICATION

ADDITIONAL PLATING 0.5oz COPPER	[Bar]	LAYER 1 TOP
0.5oz COPPER	[Bar] 0.004	LAYER 2 GND
0.5oz COPPER	[Bar] 0.046	LAYER 3 VCC
0.5oz COPPER	[Bar] 0.004	LAYER 4 BOTTOM
ADDITIONAL PLATING	[Bar]	

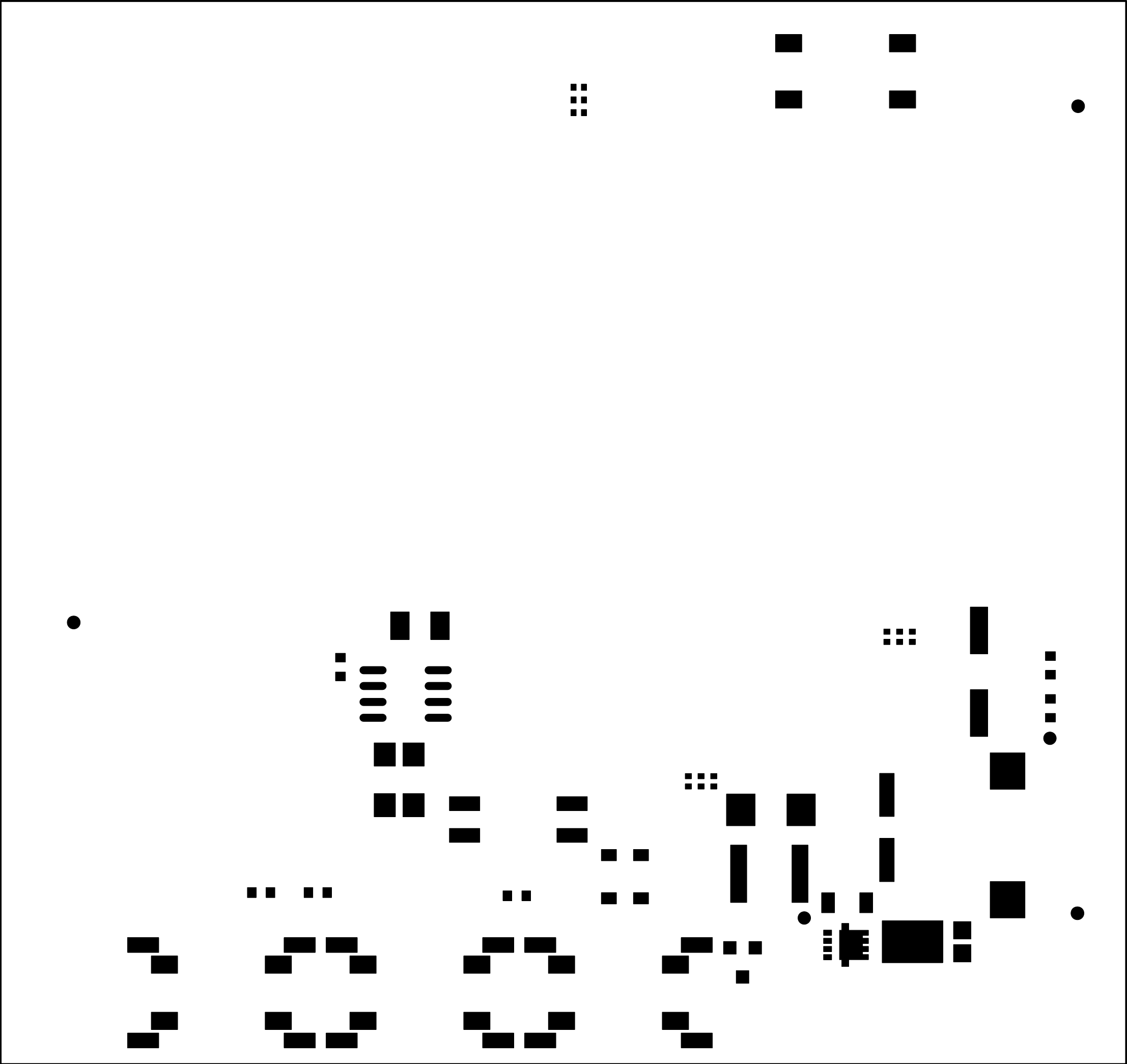
DETAIL B  
SCALE: NONE

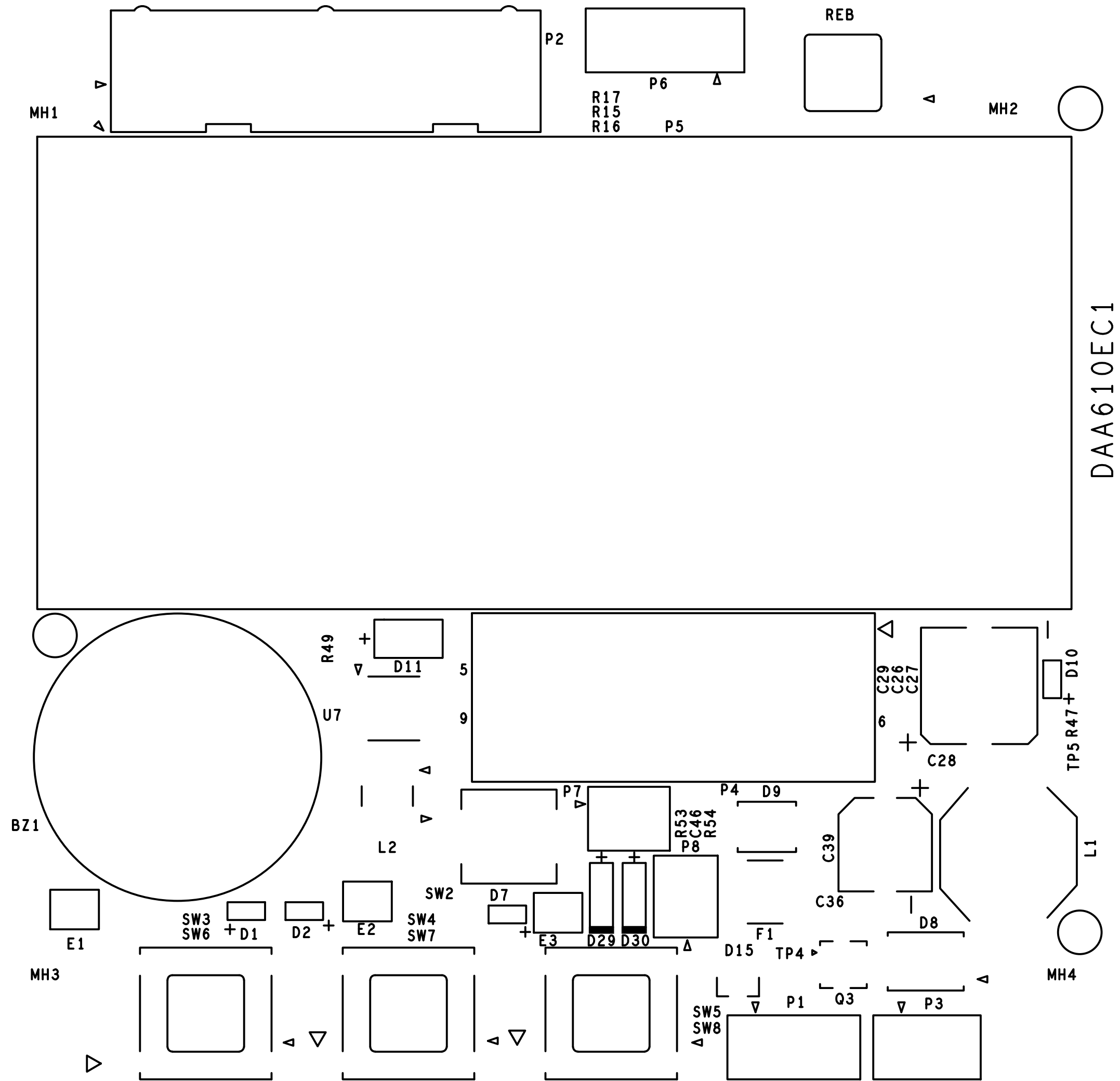
- NOTES (UNLESS OTHERWISE SPECIFIED):
1. GENERAL
    - 1.0 PWB MUST BE ROHS/WEEE COMPLIANT.
    - 1.1 STANDARDS-ALL RAW CARDS MUST CONFORM TO IPC-6012 CLASS 2 USING THE MOST CURRENT REVISION LEVEL.
    - 1.2 FOR INSPECTION, BOARDS MUST MEET THE REQUIREMENTS OF THE ACCEPTABLE LEVEL OF IPC-600 USING THE MOST CURRENT REVISION LEVEL.
  2. MATERIAL
    - 2.0 NEMA GRADE FR-4
    - 2.1 TD>=340 DEGREES C, TG>=170 DEGREES C, Z-AXIS EXPANSION <= 3.5%
    - 2.2 REFER TO DETAIL "B" FOR LAYER STACKUP AND THICKNESS.
    - 2.3 FLAMMABILITY RATING 94V-0.
  3. ETCH
    - 3.0 ETCH TOLERANCE ON ALL FOIL FEATURES INCLUDING FINISHED TRACE WIDTH AND SPACING TOLERANCE IS +/-20% OF THE ORIGINAL ARTWORK/GERBER DESIGN.
  4. FINISH
    - 4.0 PLATE THRU WITH COPPER.
    - 4.1 ELECTROLESS NICKEL IMMERSION GOLD IN ACCORDANCE WITH IPC-4552.
  5. IMPEDANCE CONTROL
    - 5.0 REFER TO DETAIL "A" FOR IMPEDANCE CONTROL TARGETS.
  6. SOLDERMASK
    - 6.0 VENDOR MUST USE THE ARTWORK SUPPLIED. THIS ARTWORK MAY CONTAIN VIAS THAT ARE PARTIALLY COVERED (ENCROACHED) WITH SOLDERMASK. ON NON-VIA HOLES AND SURFACE MOUNT PADS THERE SHOULD BE NO SOLDERMASK ON PADS AND A MAXIMUM OF .004 CLEARANCE AFTER FABRICATION WITHOUT EXPOSING ANY TRACES.
    - 6.1 FOR VIAS WITH SOLDERMASK DEFINITION ON BOTH SIDES, FOLLOW GERBER TO BUILD FOR VIAS WITHOUT SOLDERMASK DEFINITION, USE SOLDERMASK TO FILL VIAS AT LEAST 80%. FOR VIAS WITH SOLDERMASK DEFINITION ON SINGLE SIDE, PLUG VIAS FROM THE SIDE WHERE THERE IS NO SOLDERMASK DEFINITION.
    - 6.2 SOLDERMASK TO BE LPI GREEN.
    - 6.3 SOLDERMASK TO BE IN ACCORDANCE WITH IPC-SM-840 CLASS H.
  7. DRILLING
    - 7.0 ALL HOLE DIAMETERS IN HOLE CHART ARE FINISHED SIZES.
    - 7.1 SSH(SPECIAL SHAPE HOLE) TO BE ROUTED AND PLATED IN ACCORDANCE WITH OUTLINE AROUND IF THERE IS SSH FEATURE IN THE DRILL CHART.
  8. MARKING
    - 8.0 MARKING TO BE WHITE.
    - 8.1 MARKING NOT TO ENCROACH ON SURFACE MOUNT LANDS.
  9. VENDOR OPTIONS/REQUIREMENTS
    - 9.0 REMOVAL OF NON-FUNCTIONAL PADS NEED WRITTEN APPROVAL FROM JABIL.
    - 9.1 ANY THIEVING ON INTERNAL OR EXTERNAL LAYERS NEED WRITTEN APPROVAL FROM JABIL. IF THIEVING IS ALLOWED, THE MINIMUM SPACING TO CONDUCTIVE FEATURES IS .100"
    - 9.2 REPLACE THE TEXT IN THIS AREA WITH VENDOR COMPANY LOGO, UL LOGO, DATE CODE, AND UL FLAMMABILITY RATING.
    - 9.3 X-OUT IS NOT ALLOWED WITHOUT WRITTEN APPROVAL FROM JABIL.
    - 9.4 ANY OTHER CHANGES NEED WRITTEN APPROVAL FROM JABIL.
  10. NETLIST
    - 10.0 NETLIST SUPPLIED IN IPC-D-356 FORMAT.
  11. BACKDRILL
    - 11.0 IF THE BOARD REQUIRES BACKDRILL, ALL BACKDRILL HOLES ARE NON-PLATED.
    - 11.1 REMOVE THE PADS AT STARTING LAYER FOR BACKDRILL HOLES IF NECESSARY.
  12. ELECTRICAL TEST
    - 12.0 PWB MUST BE TESTED PER IPC-9252 USING SUPPLIED IPC-D-356 NETLIST.
    - 12.1 ELECTRICAL TEST CERTIFICATION MARK "ET" IS STAMPED USING PERMANENT, NON-CONDUCTIVE ROHS COMPLIANT INK.
    - 12.2 THE STAMP SHALL BE PLACED IN A LOCATION FREE OF PADS, TEST POINTS, FIDUCIALS, OR OTHER MARKINGS.
    - 12.3 EACH INDIVIDUAL BOARD IN ARRAY FORM SHALL BE STAMPED.

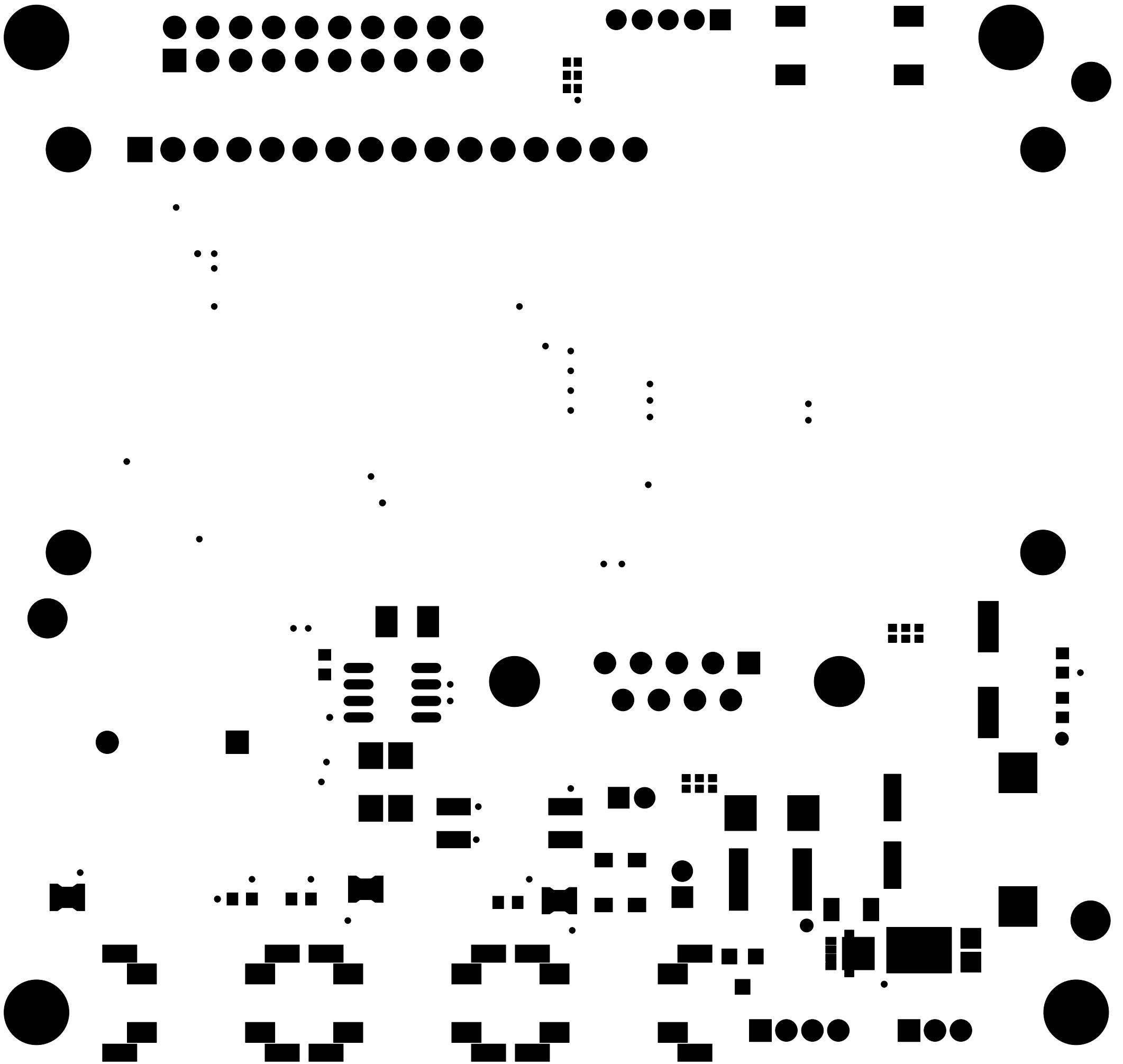
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		OTIS ENGINEERING CENTER	
		SHANGHAI	
		MATERIAL :	DRAWN APPLE GUO
SPEC:	CHK VINCENT TIAN	14 SHEETS SHEET 1	
FINISH:	APPD VINCENT TIAN		
	AUTH CN831799		

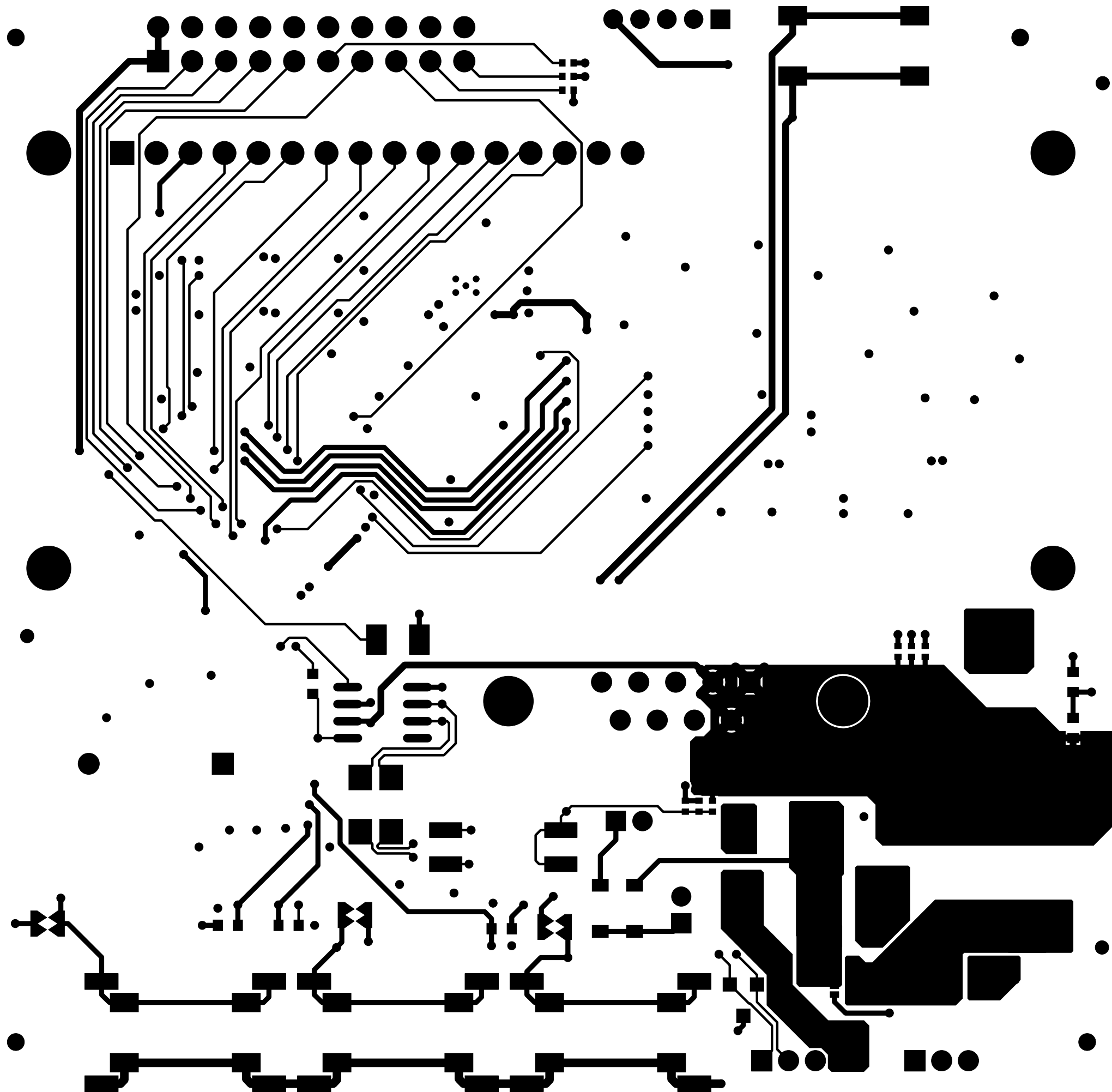


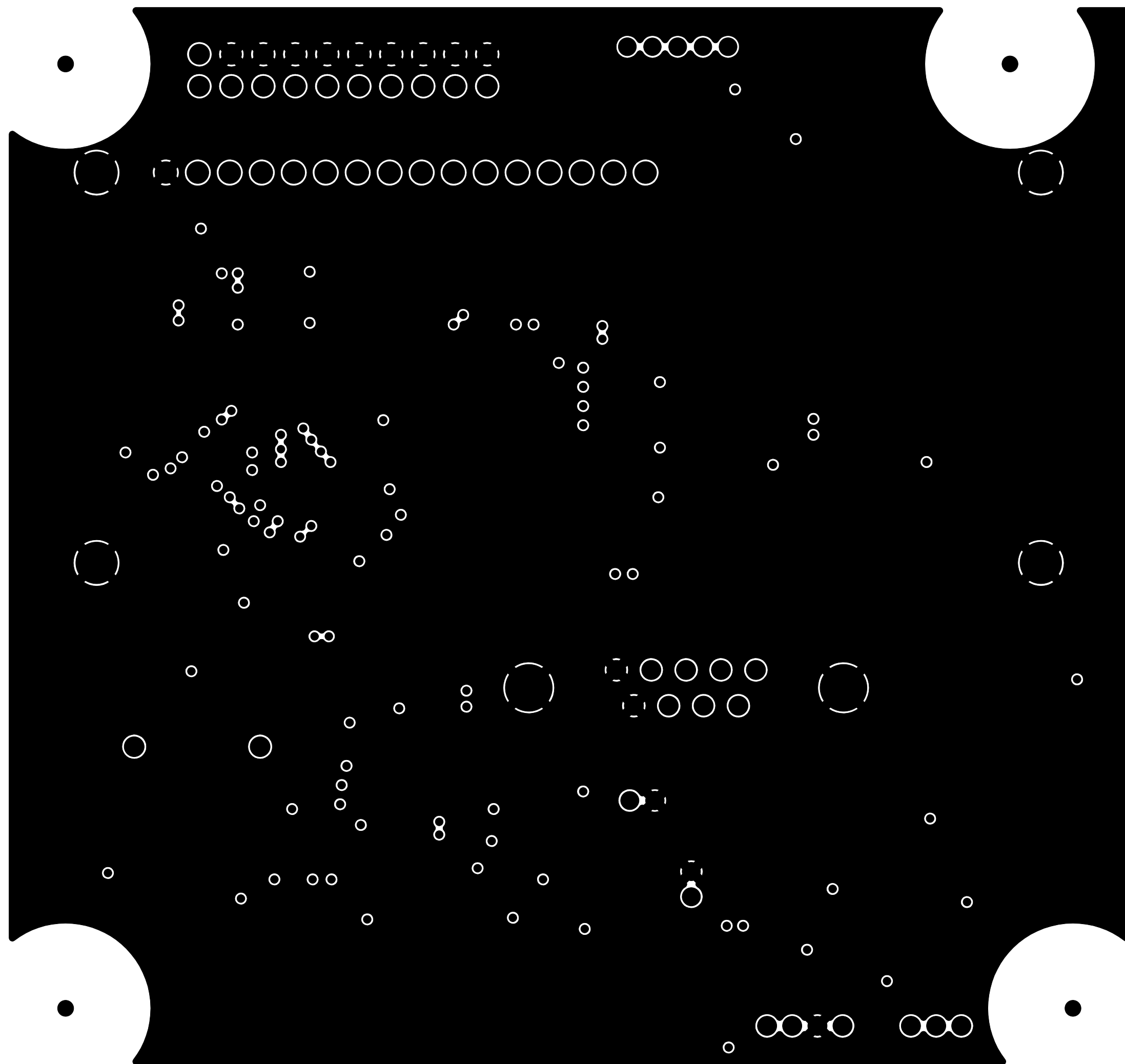
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								CHK VINCENT TIAN		2016-04-08
						SPEC:		APPD VINCENT TIAN		SHEETS
						FINISH:		AUTH CN831799		SHEET
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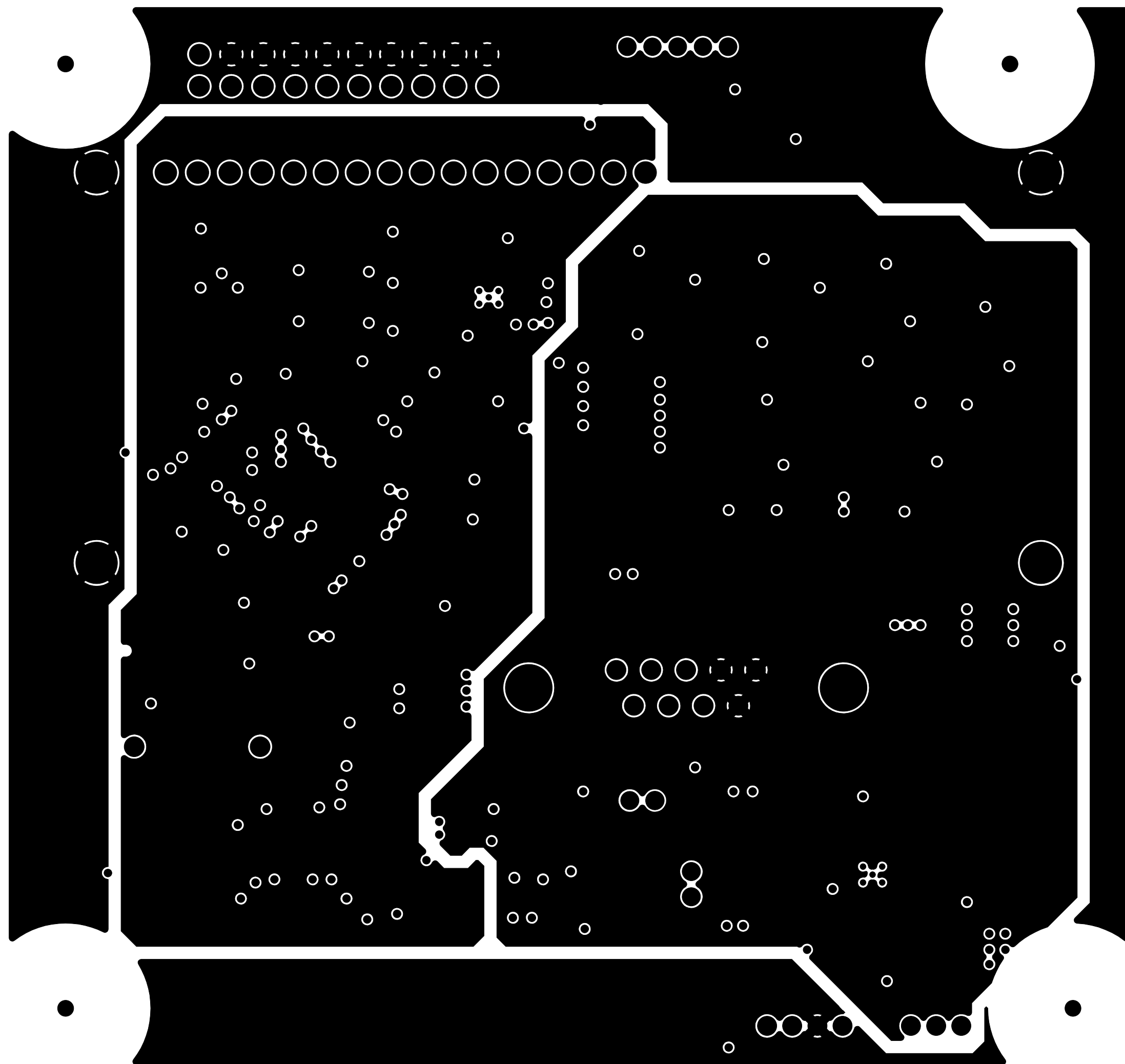




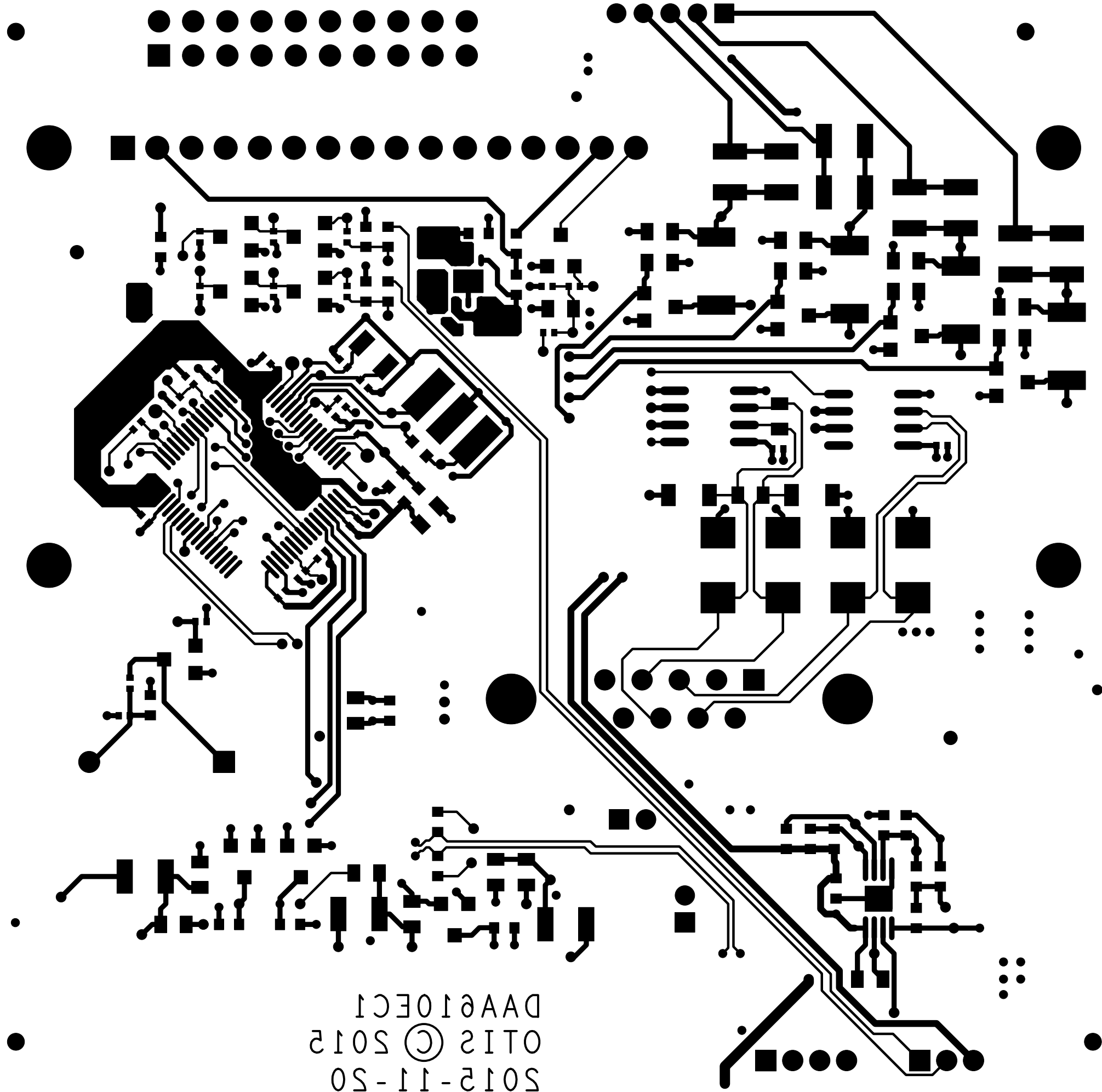




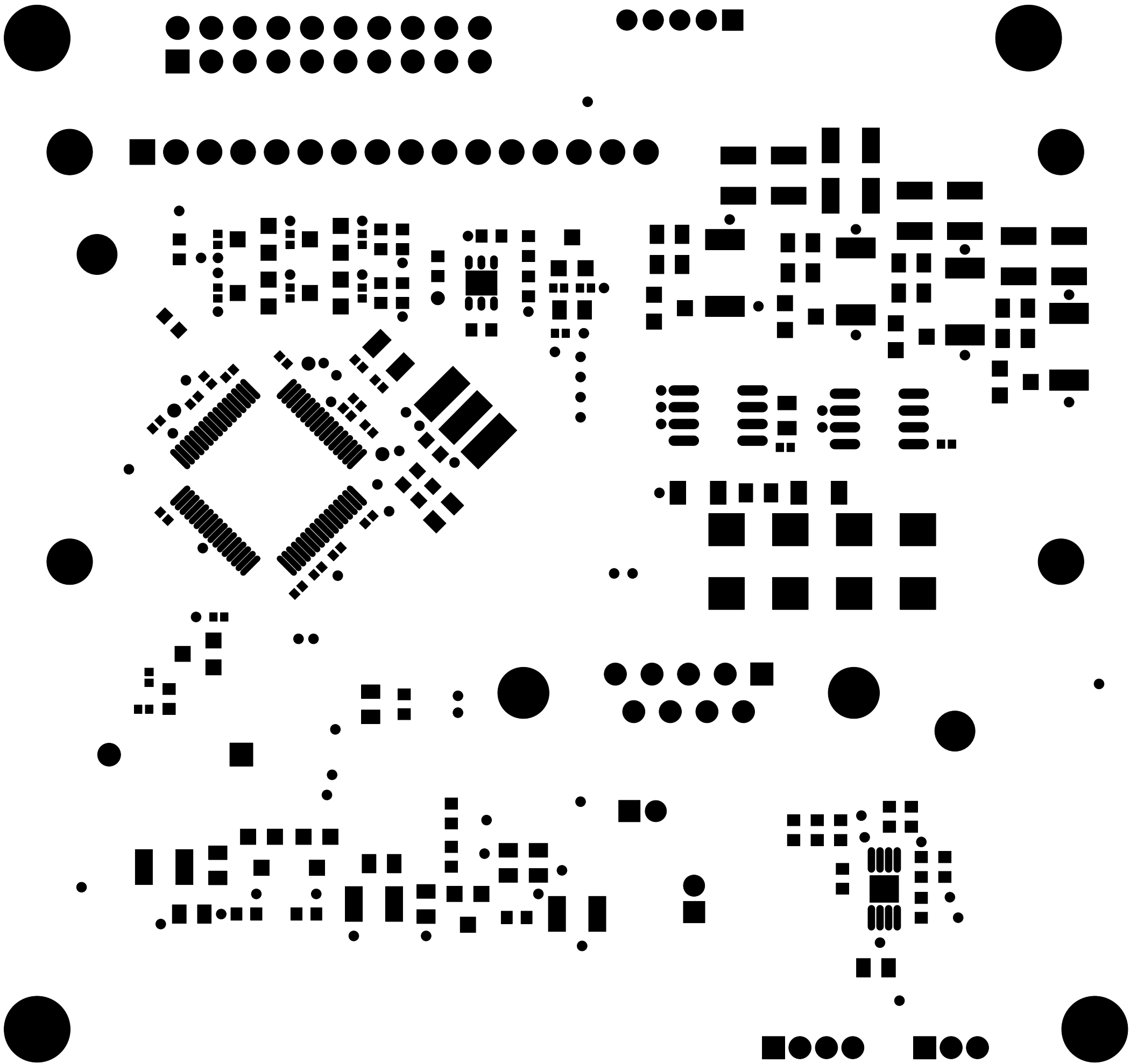




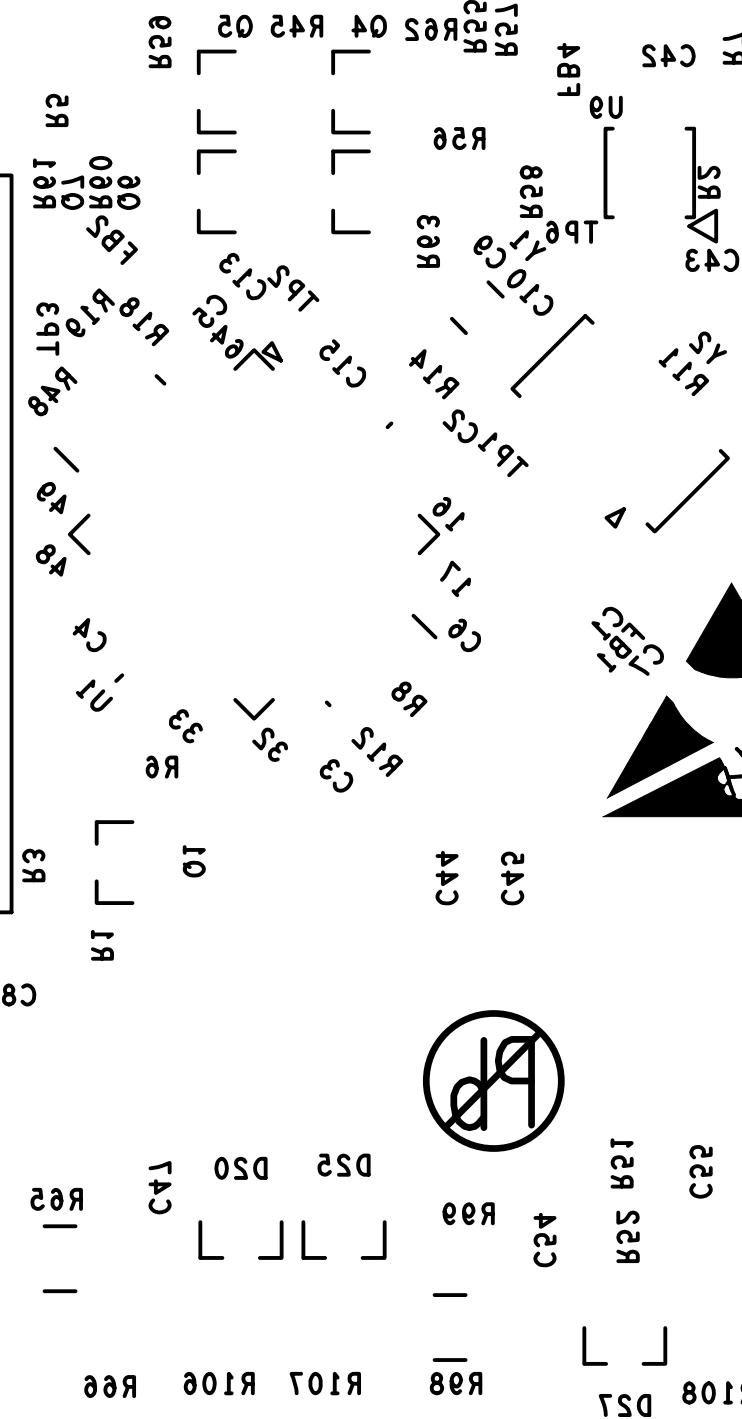
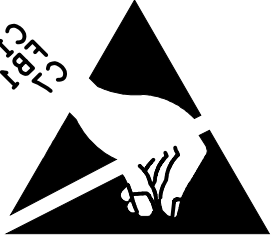
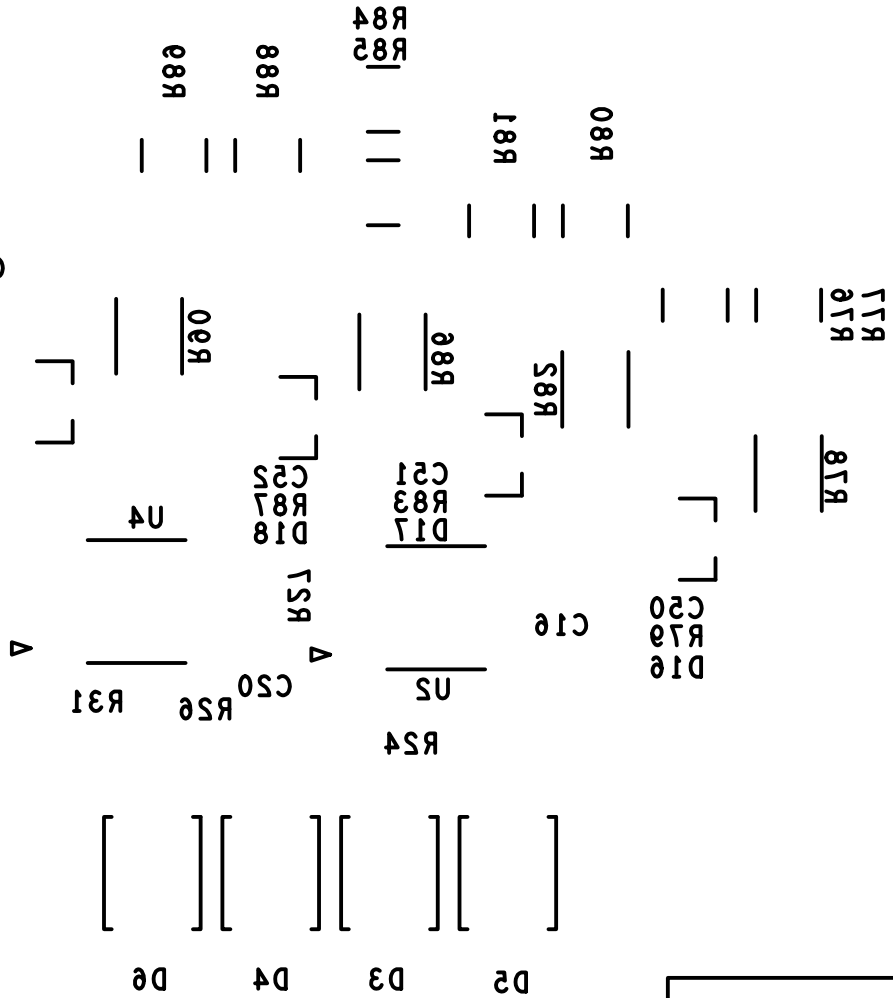




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